

APPENDIX TO RESPONSE TO OFFICIAL ACTION DATED MAY 9, 2002
AMENDMENTS TO CLAIMS
(DELETIONS IN BRACKETS AND ADDITIONS UNDERLINED)

2. (Amended) The lead-free solder comprising [according to claim 1, wherein said] an alloy composition containing [comprises] 2.0 to 5.0% by mass of silver, 0.01 to 2.0% by mass of copper, and 0.002 to 0.015% by mass of phosphorus with the balance consisting of tin.

4. (Amended) A connection lead comprising: a copper strip or other strip conductor; and a plating provided on at least one side of the strip constructor, said plating being formed of a lead-free solder composed mainly of tin,

said plating containing 0.002 to 0.015% by mass of phosphorus, 2.0 to 5.0% by mass of silver, 0.01 to 2.0% by mass of copper, with the balance consisting of tin, and having a shape such that the plating in a [the] widthwise direction of the strip conductor has a bulge as viewed in section with an [the] apex being located at a proper position in the widthwise direction of the strip conductor.

8. (Amended) An electrical component structure comprising a connection element formed of a lead-free solder composed mainly of tin,

said connection element containing 0.002 to 0.15% by mass of phosphorus, 2.0 to 5.0% by mass of silver, 0.01 to 2.0% by mass of copper, with the balance consisting of tin.